



Semiconductor Device Type: PT (V7X) 100 TQFP 12x12x1mm Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			JEDEC 97 Product Marking and/or Pkg. Labeling e3	
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	312.02	(mg) Total	Mold Compound	% of Total Weight	79.8
Silica, vitreous (or fused)	60676-86-0	Mold Compound	67.830	265.215	678,300		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	6.943	27.146	69,426		Epoxy Resin	Trade Secret	8.70	
Phenolic Resin	Trade Secret	Mold Compound	4.788	18.721	47,880		Phenolic Resin	Trade Secret	6.00	
Carbon Black	1333-86-4	Mold Compound	0.239	0.936	2,394		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	10.000	39.101	100,003		Total 100.00			
Nickel	7440-02-0	Lead Frame	0.267	1.043	2,667	41.06	(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.175	0.685	1,752		Copper	7440-50-8	95.24	
Silicon	7440-21-3	Lead Frame	0.047	0.185	473		Nickel	7440-02-0	2.54	
Magnesium	7439-95-4	Lead Frame	0.011	0.041	105		Silver	7440-22-4	1.67	
Silver	7440-22-4	Die Attach	0.555	2.170	5,550		Silicon	7440-21-3	0.45	
Epoxy resin	68475-94-5	Die Attach	0.173	0.674	1,725		Magnesium	7439-95-4	0.10	
Copper(II) oxide	1317-38-0	Die Attach	0.023	0.088	225		Total 100.00			
Silicon	7440-21-3	Chip (Die)	7.500	29.325	75,000	2.93	(mg) Total	Die Attach	% of Total Weight	0.75
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.197	0.768	1,965		Silver	7440-22-4	74.00	
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.004	0.014	35		Epoxy resin	68475-94-5	23.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	4.888	12,500		Copper(II) oxide	1317-38-0	3.00	
0.3910 g Total Mass			TOTALS:	100.000	391.000	1,000,000	Total 100.00			
						29.33	Total (mg)	Chip (Die)	% of Total Weight	7.5
							Doped Silicon	7440-21-3	100.00	
						Total 100.00				
						0.78	(mg) Total	Wire Bond Copper palladium coated (CuPd)	% of Total Weight	0.2
							Copper	7440-50-8	98.25	
							Palladium	7440-05-3	1.75	
						Total 100.00				
						4.89	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.25
							Tin	7440-31-5	100.00	
						Total 100.00				
						391.000				100.000

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at <http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/>

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at <http://echa.europa.eu/web/guest/candidate-list-table>